#### BONDING THE STARS







# Universal manual Bonder & Tester 5600

### **Bond / Tester System**

**Testheads** Pullheads – 100cN – 5000 cN

Shearheads - 500cN - 50000 cN

Tweezerhead - 100cN

**Bondheads** 5610, 5630, 5632, 5650, 5650HR

#### **Bonder / Tester Base**

Axes

Working area X/Y-axis 100x115mm

• Step resolution 0,25µm

Repeatability < 2µm</li>

Hardware

• Dual Core PC, 1,6 GHz processor,

4 GB RAM, Ethernet, 4x USB-Hub Front

• Firewire CCD colour camera 1,4 MPixel

Network-capable with TCP / IP server

Software

 Statistics such as mean value, standard deviation, trend, cp, cpk, etc. Based on SQL Databanc

Export Format SQL, CSV, HTML

**Speed** Test speed from 0.2 to 5mm/s

**Dimenstions** W x D x H - 70 x 65x 70 cm, weight approx. 80kg

**Connections** 100-240 VAC, 1 Phase, 50/60 Hz, max 500 VA

Ø 6mm standard vacuum tubing

#### The 5600:

The manual bond tester 5600 complements F&S Bondtec Semiconductor GmbH die- and wire- bonders. The PC controlled moving table allows any number of bonds to be tested automatically from a stored program.

Results can be analysed and output immediately or exported in a number of data base formats for subsequent analysis as desired. Powerful extended capabilities enable measurements such as force/time or force/distance curves to be made and deliver more data about the quality of the bond tested.

Exchangeable measurement cartridges ensure rapid conversion to different force ranges. The calibration curves of all measurement cartridges are stored internally; additional heads for shear, peel and tweezer testing with customer-specific tools and jaws are available.

After a first programming a reproducible pull- or sheartest can be guaranteed for all following components.

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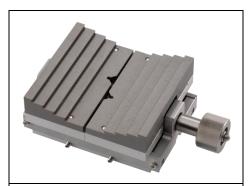


#### Workholder

Standard-Workholder for parts up to 4x4" with Vacuum und mechanical clamping



## Optional:



workholders up to 4x4" with jaws



TO workhoder with mechanical clamping



**4x4" workholder** with . rubberized surface and mechanical clamping

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